

Features

- High isolation 5000 VRMS
- Peak Breakdown Voltage
 - 600V CT3061, CT3062, CT3063
 - 800V CT3081, CT3082, CT3083
- Operating Temperature range 55 °C to 100 °C
- External Creepage ≥ 7.4mm
- Distance Through Isolation ≥ 0.4mm
- Clearance Distance ≥ 7.5mm (S/SL Type)
- Clearance Distance ≥ 8.0mm (M/SLM Type)
- RoHS and REACH Compliance
- Halogen Free Compliance (Optional)
- MSL class 1
- Regulatory Approvals
 - ✓ UL UL1577 (E364000)
 - ✓ VDE EN60747-5-5 (40039590)
 - ✓ CQC GB4943.1, GB8898 (14001105802)
 - ✓ IEC62368 (FI/41119)

Description

The CT3061, CT3062, CT3063, CT3081, CT3082 and CT3083 series consists of a Zero Cross Photo Triac optically coupled to an Infrared-emitting diode in a 6-lead DIP DMC-Isolator® package with different lead forming options.

Applications

- Motor Controls
- Lamp ballasts
- Static AC Power Switch
- Solenoid/ Valve Control

Package Outline Schematic Anode 1 6 MT1 Cathode 2 4 MT2



Absolute Maximum Ratings $T_A = 25^{\circ}C$, unless otherwise specified

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters		Ratings	Units	Notes
Viso	Isolation voltage (AC, 1	minute, 40 ~ 60% R.H.)	5000	V _{RMS}	
Topr	Operating temperature		-55 ~ +100	°C	
Тѕтс	Storage temperature		-55 ~ +150	°C	
TsoL	Soldering temperature (For 10 seconds)	260	°C	
Emitter			·	<u>. </u>	
l _F	Forward current		60	mA	
I _{F(TRANS)}	Peak transient current	(≤1µs P.W,300pps)	1	А	
V _R	Reverse voltage		6	V	
P _D	Power dissipation		100	mW	
Detector	r		·	<u>. </u>	
PD	Power dissipation		300	mW	
	Off-State Output CT3061,CT3062,CT3063		600	V	
V_{DRM}	Terminal Voltage CT3081,CT3082,CT3083		800	V	
I _{TM}	RMS on-state current		100	mA	
I _{TSM}	Peak Repetitive Surge (Current	1	А	
TJ	Junction temperature		<110	°C	



Electrical Characteristics $T_A = 25^{\circ}\text{C}$, unless otherwise specified

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I _F =10mA	-	-	1.5	V	
I _R	Reverse Current	V _R = 6V	-	-	5	μΑ	
Cin	Input Capacitance	f= 1MHz	-	45	-	pF	

Detector Characteristics

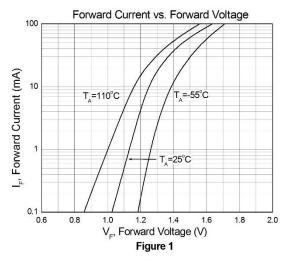
Symbol	Parameters		Test Conditions	Min	Тур	Max	Units	Notes
I	Peak Blocking	CT3061,62,63	La Om A Vasar Dated Vasar	-	-	500	^	
DRM1	Current	CT3081,82,83	I _F = 0mA, V _{DRM} = Rated V _{DRM}				nA	
lanu.	Inhibit Leakage Current		I _F = Rated I _{FT} , V _{DRM} = Rated	-	-	500		
I _{DRM2}			VDRM				μΑ	
VINH	Inhibit Voltage		I _F = Rated I _{FT} ,	-	-	20	V	
V_{TM}	Peak On-State Voltage		I _F = Rated I _{FT} , I _{TM} = 100mA	-	-	3	V	
	Critical Rate of	CT3061,62,63		1000	-	-		
dv/dt	Rise off-State	CT3081,82,83	VPEAK= Rated VDRM	600		-	V/µs	
	Voltage				-			

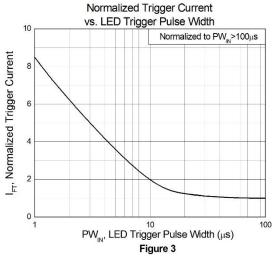
Transfer Characteristics

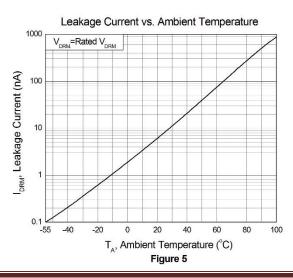
Symbol	Parameters		Test Conditions	Min	Тур	Max	Units	Notes
	Input	CT3061, CT3081	Terminal Valtage - 2V	ı	ı	15		
I _{FT}	Trigger	CT3062, CT3082	Terminal Voltage = 3V	-	-	10	mA	
	Current	CT3063, CT3083	- I _{TM} =100mA	-	-	5		
IH	Holding Current		Terminal Voltage from "ON" to "OFF"	-	380		4	
IH	Tiolding Ct	ment	"ON" state I _F =0mA	-	360	_	μΑ	
Rıo	Isolation Resistance		V _{IO} = 500V _{DC}	1x10 ¹¹	ı	-	Ω	
Cıo	Isolation Capacitance		f= 1MHz	-	0.25	-	pF	

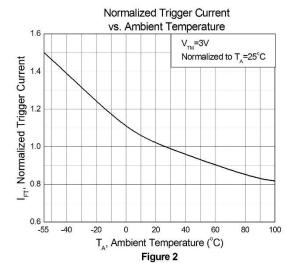


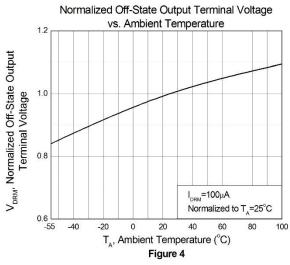
Typical Characteristic Curves $T_A = 25$ °C, unless otherwise specified

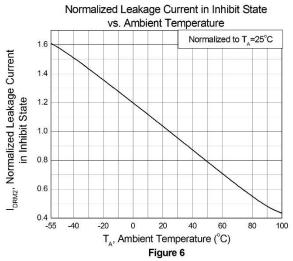






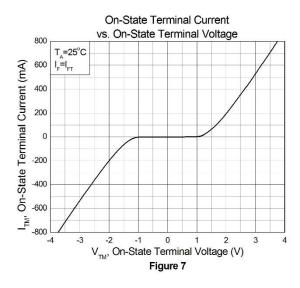


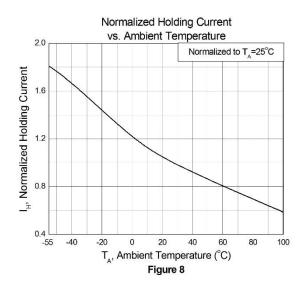


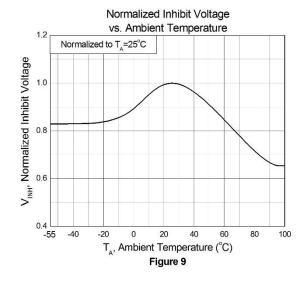




Typical Characteristic Curves $T_A = 25$ °C, unless otherwise specified (Continued)

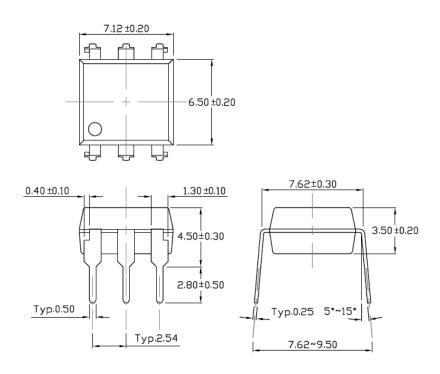




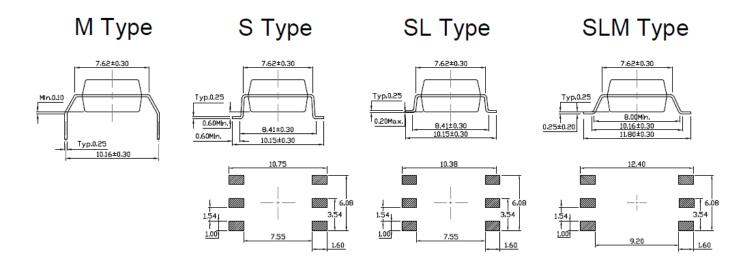




Package Dimension Dimensions in mm unless otherwise stated

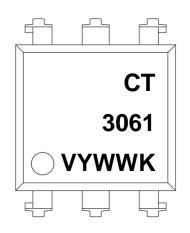


Forming Option Dimensions in mm unless otherwise stated





Marking Information



Note:

CT : Denotes "CT Micro"

3061 : Part Number

X : CTR Rank Option (Blank, A or B)V : VDE Safety Mark Option (Blank or V)

Y : One Digit Year CodeWW : Two Digit Work WeekK : Manufacturing Code

Ordering Information

CT306X(V)(Y)(Z)-G, CT308X(V)(Y)(Z)-G

CT = Denotes "CT Micro"

= Part No. (CT306X:1,2,3), (CT308X:1,2,3)

V = VDE Safety Mark Option (Blank or V)

Y = Lead Form Option (Blank, S, SL, M or SLM)

Z = Tape and Reel Option (Blank, T1 or T2)

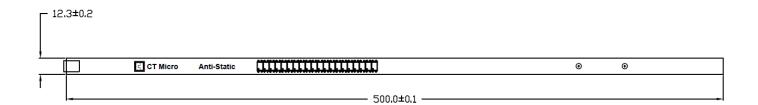
G = Material Option (G: Halogen Free, Blank: Non-Halogen Free)

Option	Description	Quantity
None	Standard 6 Pin Dip	50Units/Tube
M	Gullwing (400mil) Lead Forming	50Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1000 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	1000 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming – With Option 2 Taping	1000 Units/Reel
SLM(T1)	Surface Mount (Gullwing) Lead Forming– With Option 1 Taping	1000 Units/Reel
SLM(T2) Surface Mount (Gullwing) Lead Forming – With Option 2 Taping		1000 Units/Reel

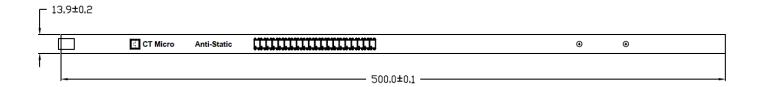


Carrier Specifications Dimensions in mm unless otherwise stated

Tube Option Standard DIP

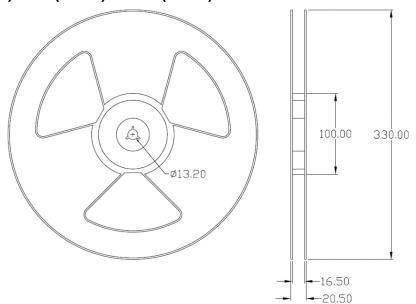


Tube Option M Type



Reel Dimension Dimensions in mm unless otherwise stated

Option S(T1/T2) & SL(T1/T2) & SLM(T1/T2)





Carrier Tape Specifications Dimensions in mm unless otherwise stated

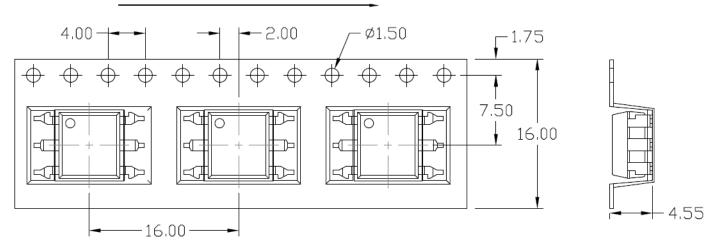
Option S(T1) & SL(T1)

Option S(T2) & SL(T2)



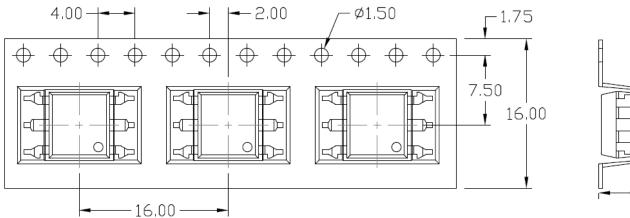
Option SLM(T1)

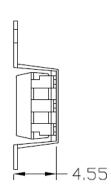
Input Direction



Option SLM(T2)

Input Direction







Solderability Specification (follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

Wave soldering (follow the JEDEC standard JESD22-A111)

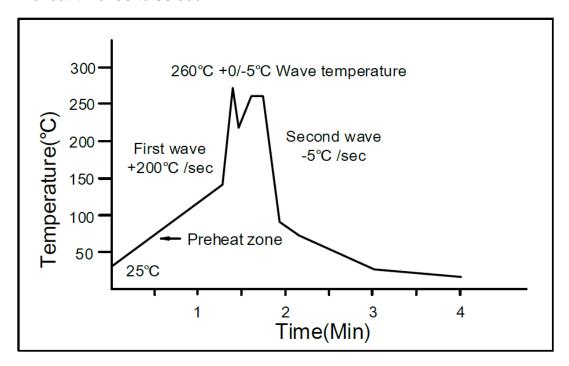
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature:25 to 140°C.

Preheat time: 30 to 80 sec.



Iron Soldering (follow the standard MIL-STD 202G, Method 210F)

Allow single lead soldering in every single process.

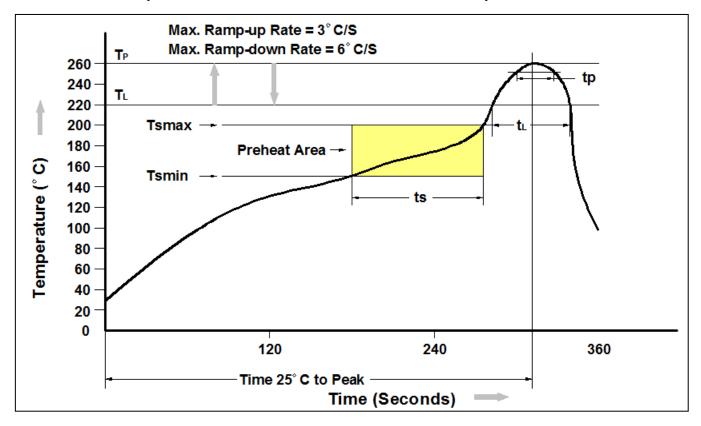
One time soldering is recommended.

Temperature: 350±10°C

Time: 5 sec max.



Reflow Profile (follow the JEDEC standard J-STD-020)



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t⊳)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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